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## Koh Young Launches the Meister D+ for Semiconductor Package Inspection to the Americas Market

Atlanta, GA – Koh Young, the industry leader in True3D™ measurement-based inspection solutions, announces the release of its new Meister D+ semiconductor inspection solution. Premium True3D™ Inspection Solution for Chiplets and System-in-Package (SiP) devices including die and surface mount components. The new Meister D+ is an extension of the Meister product family that features solutions ranging from solder paste, printed bumps, and solder ball to small components like 0201Ms and highly reflective die.

### Meister D+: Industry Leading Inspection Systems for Advanced Packaging and Semiconductor Applications

As advanced packages continue evolving, device thickness is paramount since consumers demand smaller products with more functionality. As such, the die must be thinned, which creates a mirror-like surface that challenges optical inspection due to its highly reflective surface. Additionally, tight interspacing and increasing aspect ratios further complicate inspection. Yet, as the name implies, the Meister D+ dominates these challenges with industry leading True3D measurement accuracy and inspection technologies.

The latest Meister D+ system is perfected for component and die inspection, while delivering fast, accurate inspection from an 8-projector probe. It targets MCM/SiP/Chiplet inspection with integrated measurement and defect analysis software built on a proprietary AI engine. Beyond 0201M (008004) microchips, 10um bump height, and 5um gap spacing, it detects die defects like micro-cracks, chippings, and foreign material with high accuracy/repeatability. Additionally, this 3D solution supports a wide range of inspection capabilities: missing, offset, rotation, polarity, dimension, co-planarity, and more.

With its Moiré technology, new 12MegaPixel/5-micron optics, and 300mm<sup>2</sup>/second inspection speed, the Meister D+ is the first solution for production-speed 3D inspection for modules combining microchips and mirror-finish die. With its user-friendly GUI and programming wizards, it virtually eliminates fine-tuning and teaching, which quickens the production ramp. Plus, its IPC-CFX-2591, IPC-HERMES-9852, and IPC-DPMX-2581 compatibility makes connectivity simple and secure.

With innovative technologies, Meister D+ delivers best-in-class performance and functionality. Its inspection capabilities have already been qualified for mass production by major semiconductor companies throughout the world. The recognized leader in electronics measurement and inspection, Koh Young continues to deliver solutions for the electronics manufacturing industry.

To learn more about our award-winning technologies from Koh Young, visit us at SMTA International in booth 3319. As the Premiere Sponsor for SMTA International, Koh Young America is excited to reconnect and collaborate in-person, while ensuring COVID safety protocols are implemented and upheld for your health and ours. You can register to attend the in-person conference and exposition at [smta.org/mpage/smtai](https://smta.org/mpage/smtai). If you cannot attend, you can still learn more about our best-in-class inspection solutions at our regional website [www.kohyoungamerica.com](https://www.kohyoungamerica.com).



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**About Koh Young Technology, Inc.**

Established in 2002, Koh Young pioneered the market by launching the first 3D Solder Paste Inspection (SPI) system using a patented dual-projection Moiré technology. Since then, it has become the global leader in 3D measurement-based SPI and Automated Optical Inspection (AOI) equipment for the electronics industry. Based on its True3D™ measurement-based inspection technology, Koh Young has developed innovative solutions for challenges with Machining Optical Inspection (MOI), Dispensing Process Inspection (DPI), and Semiconductor Packaging Inspection (MEISTER Series). Through its technology innovations, Koh Young has secured thousands of global customers, and maintains the largest global market share in the SPI and AOI markets. Additionally, by adopting its user-centric R&D activities, it continues to leverage core competencies and develop innovative solutions for new and existing markets. Its activities stem from the corporate headquarters in Korea to its global sales and support offices in Europe, Asia, and the Americas. These local facilities ensure it keeps in close contact with the market, and more importantly, its growing customer base to provide access to an award-winning network of inspection and measurement experts. Learn why so many electronics manufacturers trust Koh Young for reliable inspection at [kohyoung.com](http://kohyoung.com).

**For More Information**

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